

## NCE P-Channel Enhancement Mode Power MOSFET

### Description

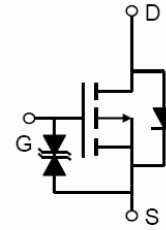
The NCE01P03S uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. It is ESD protected.

### General Features

- $V_{DS} = -100V, I_D = -3A$   
 $R_{DS(ON)} < 200m\Omega @ V_{GS} = -10V$  (Typ:170m $\Omega$ )  
 $R_{DS(ON)} < 230m\Omega @ V_{GS} = -4.5V$  (Typ:200m $\Omega$ )
- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low on-resistance

### Application

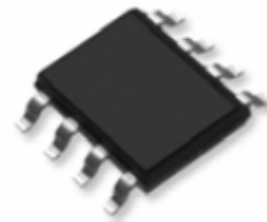
- Power switch
- DC/DC converters



Schematic diagram



Marking and pin assignment



SOP-8 top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE01P03S	NCE01P03S	SOP-8	Ø330mm	12mm	4000 units

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-3	A
Drain Current-Continuous( $T_C = 100^\circ C$ )	$I_D(100^\circ C)$	-2.1	A
Pulsed Drain Current	$I_{DM}$	-20	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	50	$^\circ C/W$
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**Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)**

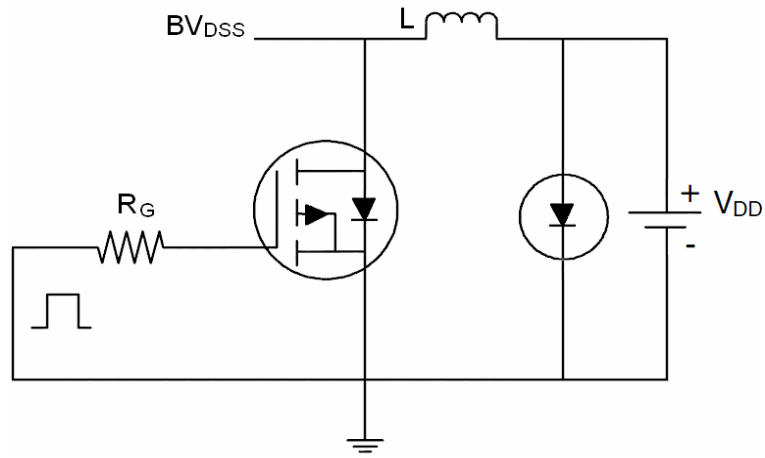
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±10	μA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1	-1.9	-3	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A	-	170	200	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A	-	200	230	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A	2	-	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V, F=1.0MHz	-	760	-	PF
Output Capacitance	C <sub>oss</sub>		-	260	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	170	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-50V, I <sub>D</sub> =-3A V <sub>GS</sub> =-10V, R <sub>GEN</sub> =9Ω	-	14	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	18	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	50	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	18	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-50V, I <sub>D</sub> =-3A, V <sub>GS</sub> =-10V	-	25	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	7	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-3A	-	-	-1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>	-	-	-	-3	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = -3A di/dt = 100A/μs (Note 3)	-	35	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	46	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=-50V, V<sub>G</sub>=-10V, L=0.5mH, R<sub>g</sub>=25Ω

**Test Circuit**

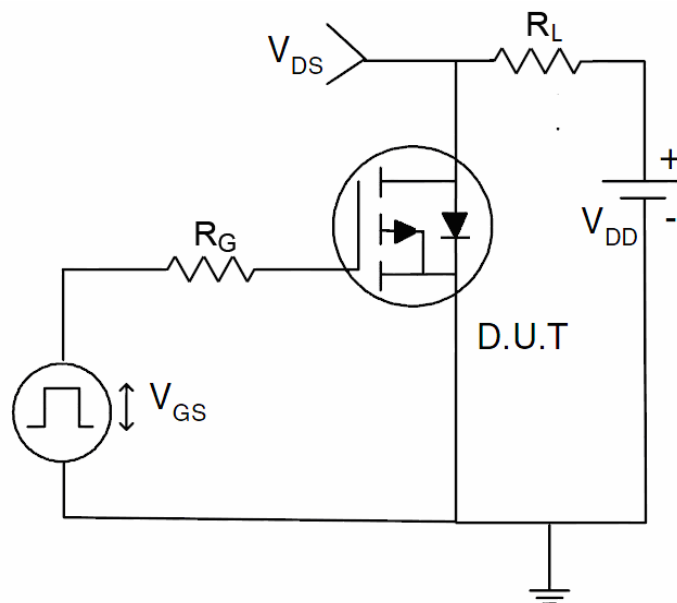
**1) E<sub>AS</sub> Test Circuit**



**2) Gate Charge Test Circuit**



**3) Switch Time Test Circuit**



Typical Electrical and Thermal Characteristics (Curves)

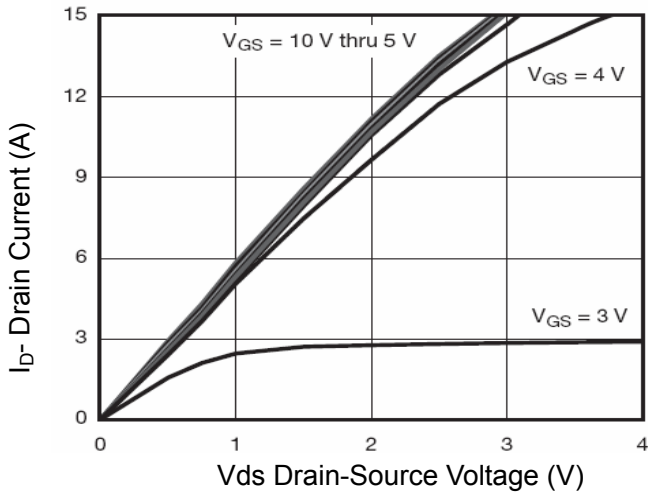


Figure 1 Output Characteristics

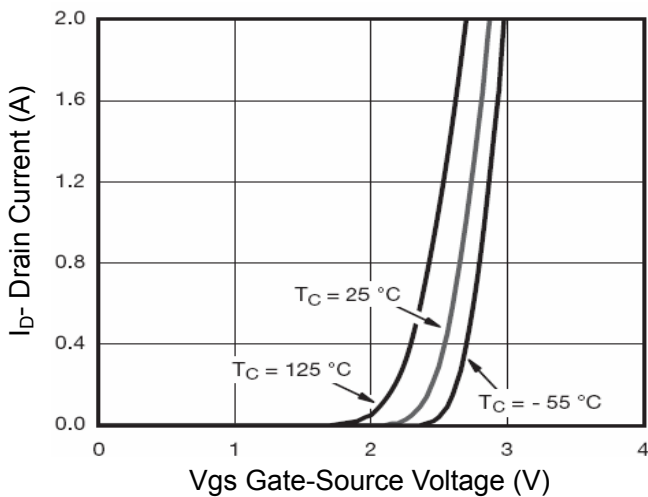


Figure 2 Transfer Characteristics

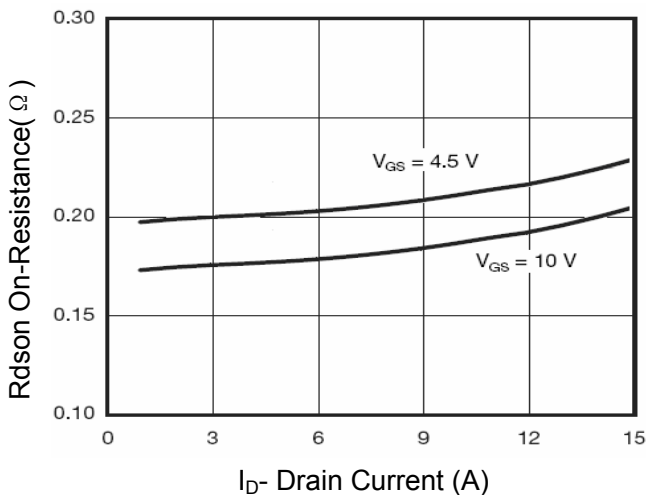


Figure 3 Rdson- Drain Current

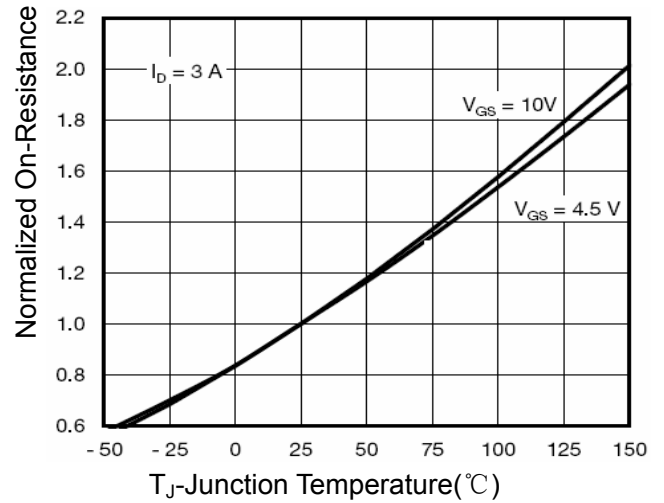


Figure 4 Rdson-Junction Temperature

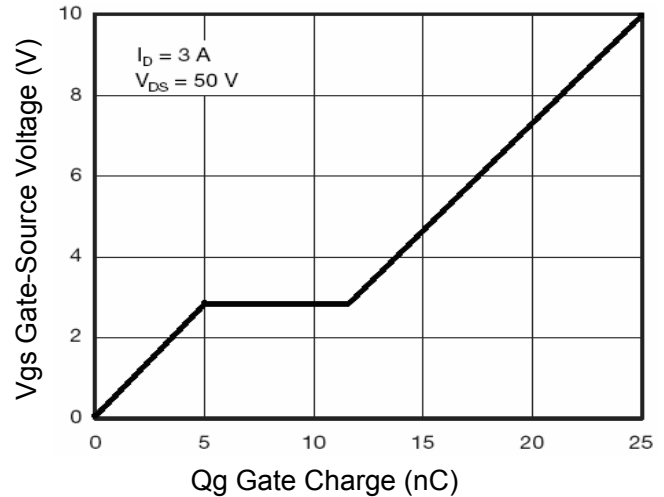


Figure 5 Gate Charge

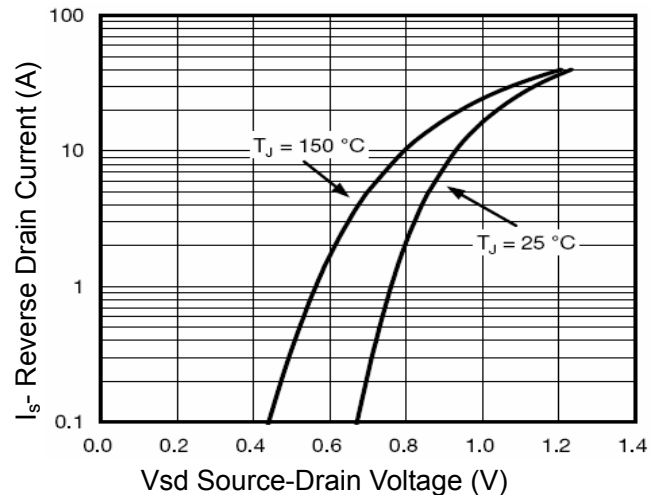


Figure 6 Source- Drain Diode Forward

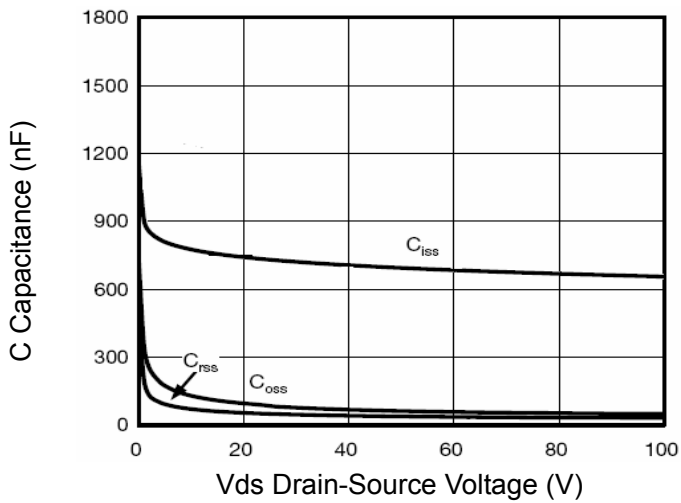


Figure 7 Capacitance vs Vds

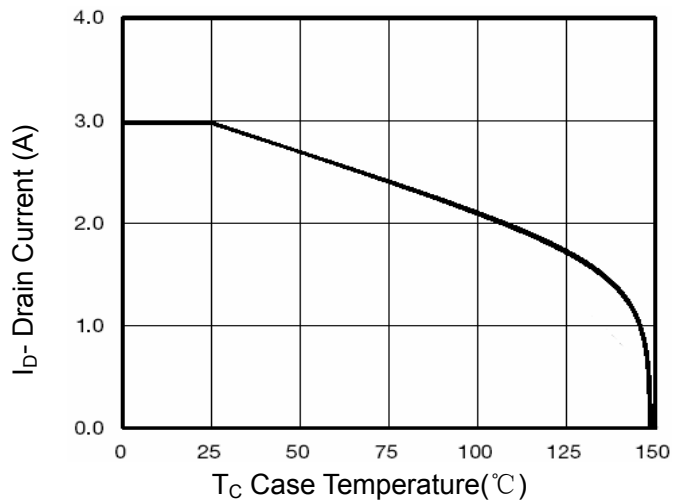


Figure 9 Drain Current vs Case Temperature

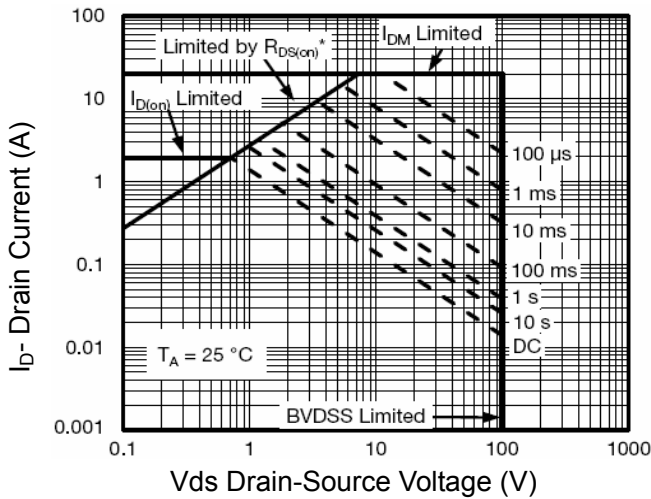


Figure 8 Safe Operation Area

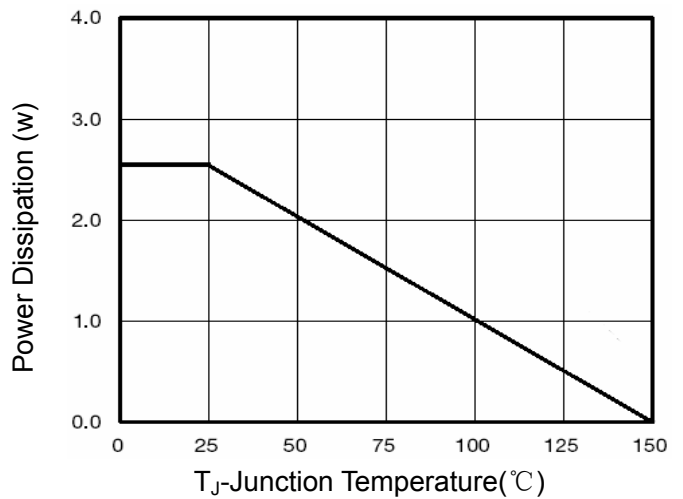


Figure 10 Power De-rating

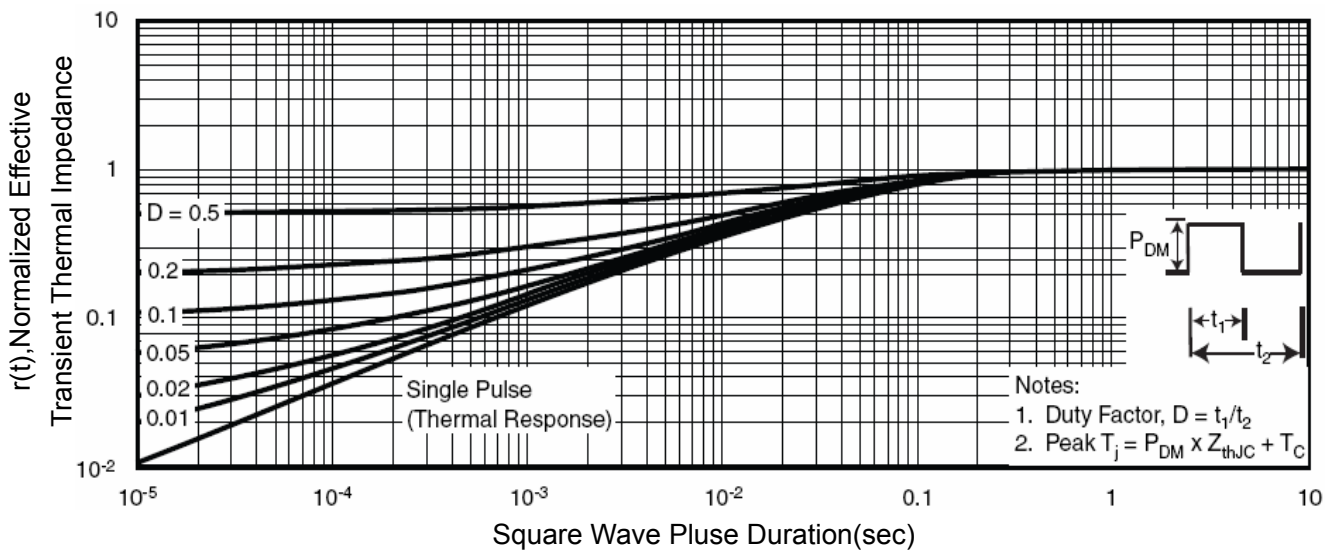
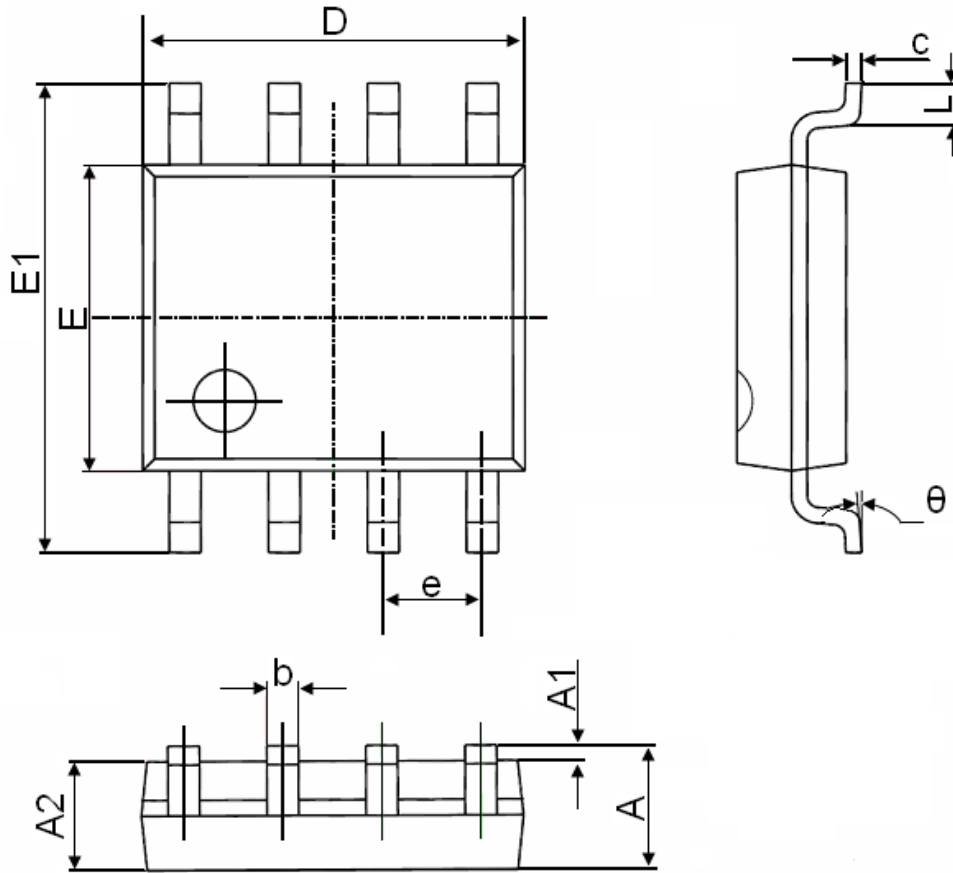


Figure 11 Normalized Maximum Transient Thermal Impedance

**SOP-8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
theta	0°	8°	0°	8°

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